

Product Advisory (PA)

Subject: Change of the standard interior label of Renesas Electronics

Publication Date: December 1, 2022

Effective Date: Refer to Appendix A to D

Revision Description:

Initial Release

Description of Change:

Renesas Electronics will update and streamline the standard interior labels in shipments for all products in conjunction with our systems integration plan.

Kindly refer to Appendix A to D for comparison on the current and new standard labels.

Materials related to 2D barcode specifications is available upon request.

Affected Product List:

All products, including legacy Intersil, IDT, Dialog and Renesas except custom-labeled products.

Reason for Change:

To integrate company-wide standard labels through the integration of SCM systems, including logistic systems.

Impact on Fit, Form, Function, Quality & Reliability:

This change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Qualification Status: Not applicable

Sample Availability Date: Not applicable

Device Material Declaration: Not applicable

Questions or requests pertaining to this change notice, including additional data, must be sent to Renesas within 30 days of the publication date.

APPENDIX A: LEGACY INTERSIL PRODUCTS

Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

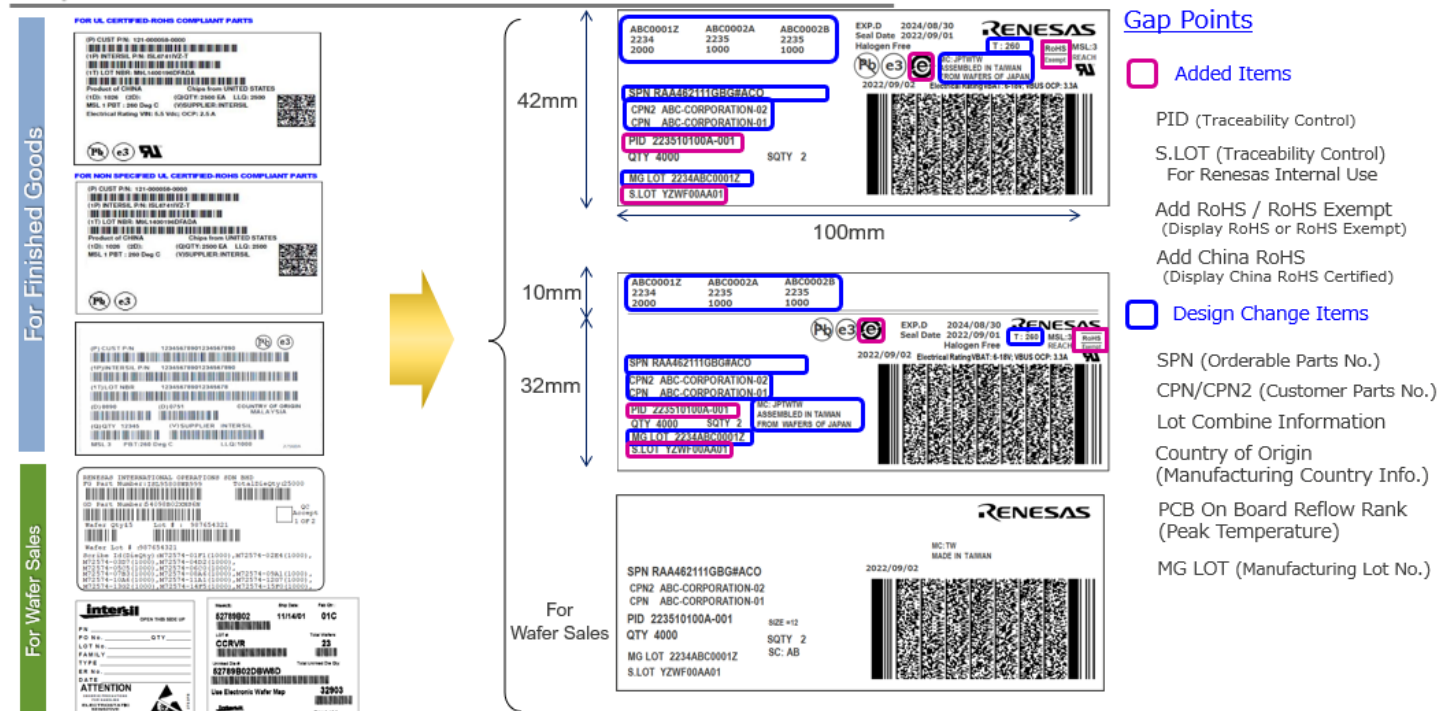
Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign

ABC0001Z 2234 2000	ABC0002A 2235 1000	ABC0002B 2235 1000	⑪ EXP.D 2024/08/30 ⑫ Seal Date 2022/09/01 ⑬ Halogen Free ⑭ Pb-Free Logo Mark ⑮ e3 ⑯ MC: JPTWTW ASSEMBLED IN TAIWAN FROM WAFERS OF JAPAN ⑰ 2022/09/02 ⑱ Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A ⑲ T: 260 ㉑ RoHS Exempt ㉒ MSL: 3 ㉓ REACH ㉔ UL
② D/N RAA462111GBG			
③ SPN RAA462111GBG#ACO AC0YE0100			
④ CPN2 ABC-CORPORATION-02 CPN ABC-CORPORATION-01			
⑤ PID 223510100A-001		SIZE =12	⑲
⑥ QTY 4000	⑳ PARTIAL ◆◆	㉑ SQTY 2	㉒
⑦ MG LOT 2234ABC0001Z		SC: AB	㉓
⑧ S.LOT YZWF00AA01		MIXED ★	㉔

ABC0001Z 2234 2000			ABC0002A 2235 1000	ABC0002B 2235 1000	EXP.D 2024/08/30 Seal Date 2022/09/01 Halogen Free ⑭ Pb-Free Logo Mark ⑮ e3 ⑯ MC: JPTWTW ASSEMBLED IN TAIWAN FROM WAFERS OF JAPAN ⑰ 2022/09/02 ⑱ Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A ⑲ T: 260 ㉑ RoHS Exempt ㉒ MSL: 3 ㉓ REACH ㉔ UL
D/N RAA462111GBG					
SPN RAA462111GBG#ACO AC0YE0100					
CPN2 ABC-CORPORATION-02 CPN ABC-CORPORATION-01					
PID 223510100A-001			SIZE =12		
QTY 4000		PARTIAL ◆◆		SQTY 2	
MG LOT 2234ABC0001Z			SC: AB		
S.LOT YZWF00AA01			MIXED ★		

Gap Points Current and New / Ex-ISL



For additional information regarding this notice, please contact your regional change coordinator (below)

Asia Pac: PCN-APAC@Renesas.COM

APPENDIX B: LEGACY IDT PRODUCTS

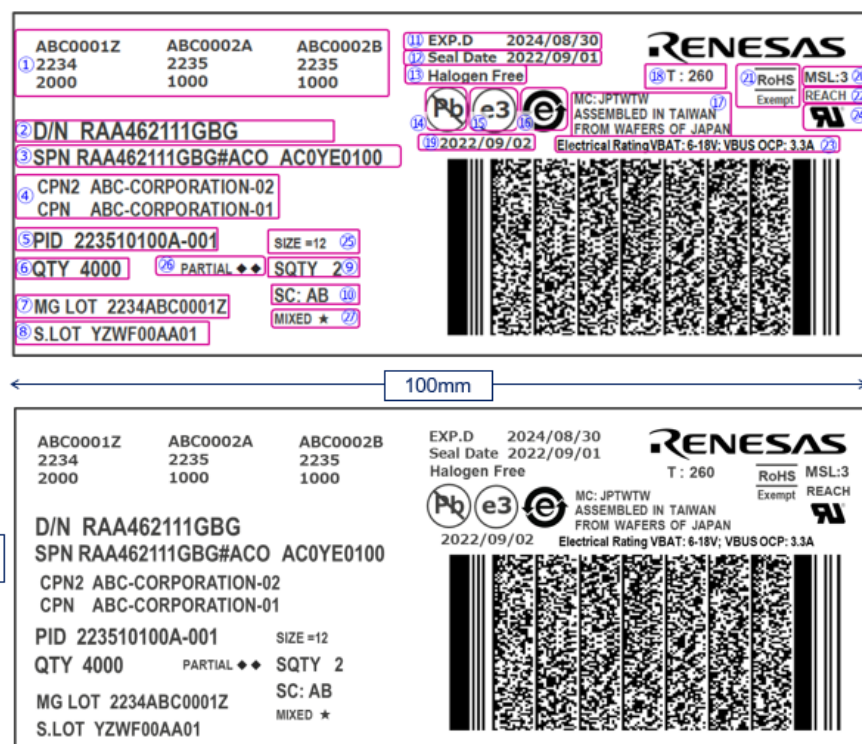
Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy IDT products

Gap Points Current and New / Ex-IDT

For Finished Goods

For Wafer Sales

➔

42mm

100mm

10mm

32mm

For Wafer Sales

Gap Points

- **Added Items**
 - PID (Traceability Control)
 - S.LOT (Traceability Control)
 - For Renesas Internal Use
- **Design Change Items**
 - SPN (Orderable Parts No.)
 - Lot Combine Information
 - MG LOT (Manufacturing Lot No.)
 - Pb-Free's Logo Mark
 - Country of Origin (Manufacturing Country Info.)
 - PCB On Board Reflow Rank (Peak Temperature)

For additional information regarding this notice, please contact Idt-pcn@lm.renesas.com.

APPENDIX C: LEGACY DIALOG PRODUCTS

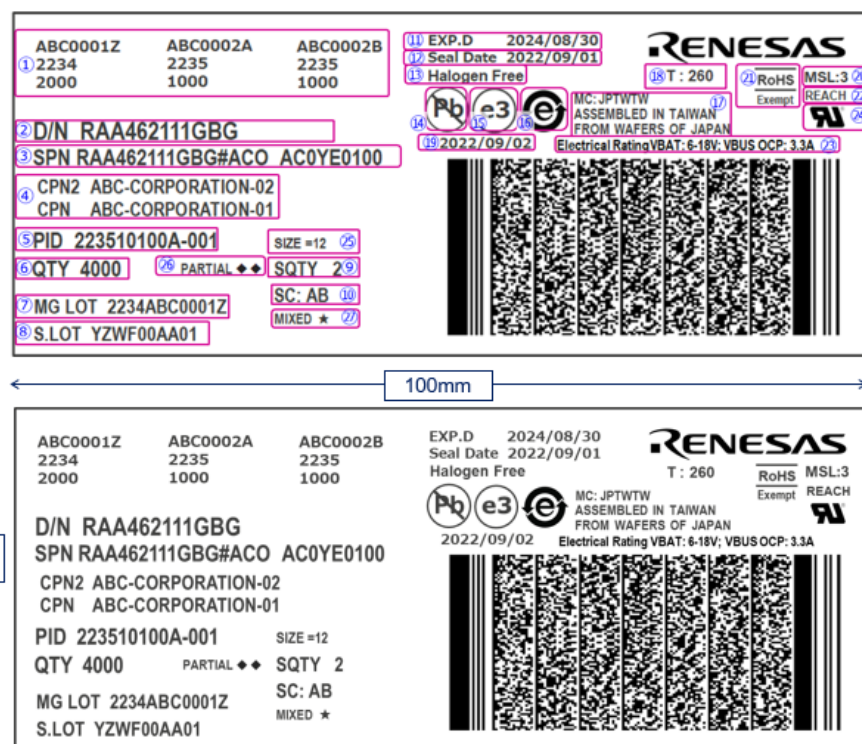
Effective Date: August 1, 2023

Product Identification:

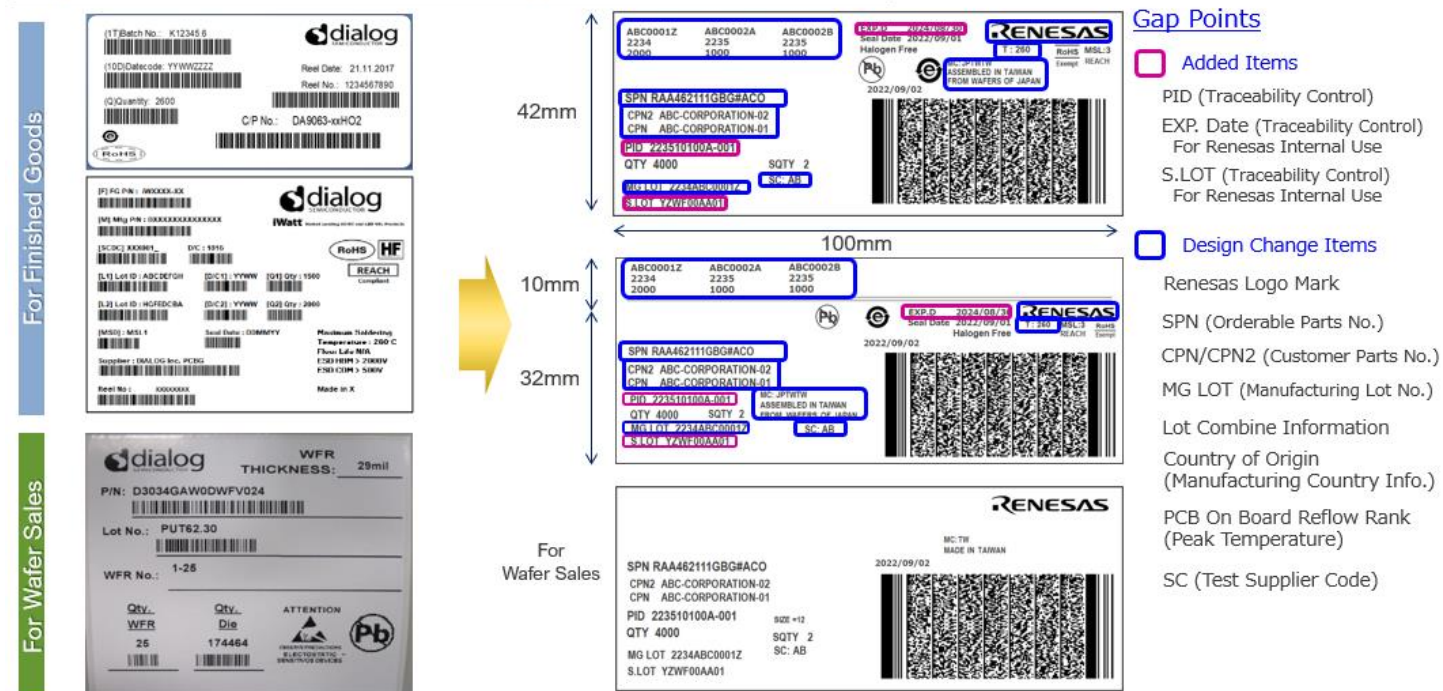
The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Gap Points Current and New / Ex-DLG



For additional information regarding this notice, please contact your Renesas sales representative.

APPENDIX D: LEGACY RENESAS PRODUCTS

Effective Date: April 1, 2024

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign

ABC0001Z ABC0002A ABC0002B

① 2234 2235 2235

2000 1000 1000

⑪ EXP.D 2024/08/30

⑫ Seal Date 2022/09/01

⑬ Halogen Free

RENESAS

⑮ T: 260

⑰ RoHS MSL:3 ㉑

⑲ 2022/09/02

⑳ MC: JPTWTW ASSEMBLED IN TAIWAN FROM WAFERS OF JAPAN

㉒ Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

② D/N RAA462111GBG

③ SPN RAA462111GBG#ACO AC0YE0100

④ CPN2 ABC-CORPORATION-02

CPN ABC-CORPORATION-01

⑤ PID 223510100A-001 SIZE =12 ㉕

⑥ QTY 4000 ㉖ PARTIAL ♦♦ ㉗ SQTY 2 ㉘

⑦ MG LOT 2234ABC0001Z SC: AB ⑩

⑧ S.LOT YZWF00AA01 MIXED ★ ㉙

100mm

ABC0001Z ABC0002A ABC0002B

2234 2235 2235

2000 1000 1000

EXP.D 2024/08/30

Seal Date 2022/09/01

Halogen Free

RENESAS

T: 260

RoHS MSL:3 ㉑

2022/09/02

MC: JPTWTW ASSEMBLED IN TAIWAN FROM WAFERS OF JAPAN

Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

D/N RAA462111GBG

SPN RAA462111GBG#ACO AC0YE0100

CPN2 ABC-CORPORATION-02

CPN ABC-CORPORATION-01

PID 223510100A-001 SIZE =12

QTY 4000 PARTIAL ♦♦ SQTY 2

MG LOT 2234ABC0001Z SC: AB

S.LOT YZWF00AA01 MIXED ★

Comparison before and after change for legacy RENESAS products

Gap Points Current and New / Renesas Japan (REL)



Gap Points

Design Change Items

- Pb-Free's Logo Mark
- PCB On Board Reflow Rank (Peak Temperature)
- Customer Parts No. (Display Name Change)
PN/PN2 => CPN/CPN2
- MG LOT (Display Name Change)
T/C => MG LOT
- PCN (Deleted Item)

For additional information regarding this notice, please contact your Renesas sales representative.